

Title (en)

MOLDS, MOLD SETS AND CASTING APPARATUS

Title (de)

FORMEN, FORMSÄTZE UND GIESSVORRICHTUNG

Title (fr)

MOULES, ENSEMBLES DE MOULES ET APPAREIL DE COULÉE

Publication

**EP 3517231 A1 20190731 (EN)**

Application

**EP 16886819 A 20160927**

Priority

- KR 20160122013 A 20160923
- KR 2016010822 W 20160927

Abstract (en)

It is an object of the present disclosure is to provide a mold, a mold set and a casting apparatus configured to easily discharge ferro silicon or ferro manganese free from generation of condensations formed with foreign objects, wherein the casting apparatus includes: a distributor distributing a molten ferrosilicon or ferro manganese; a mold part including a plurality of mold sets receiving the distribution of the molten ferrosilicon or ferro manganese from the distributor; and a feeding part feeding the mold part by passing from a first curved part and to a second curved part in a closed-circulative loop, wherein the molten ferrosilicon or ferro manganese cooled by the mold part is discharged from the first curved part, and wherein a mold set includes: a molder holder; anda plurality of molds arranged by being coupled to the mold holder, wherein the mold may be centrally formed with a cavity to be inputted with molten ferrosilicon or ferro-maganese and made with a stone material.

IPC 8 full level

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CPC (source: EP KR)

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